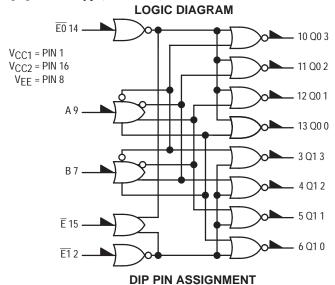
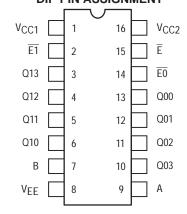
Dual Binary to 1-4 Decoder (High)

The MC10172 is a binary-coded $\underline{2}$ line to dual 4 line decoder with selected outputs high. With either $\underline{E0}$ or $\underline{E1}$ low, the corresponding selected 4 outputs are low. The common enable \overline{E} , when high, forces all outputs low.

- $P_D = 325 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 4.0 \text{ ns typ}$
- t_r , $t_f = 2.0$ ns typ (20%–80%)





Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

TRUTH TABLE

		_										
Ē	E1	E0	Α	В	Q10	Q11	Q12	Q13	Q00	Q01	Q02	Q03
L	Н	Н	L	L	Н	L	L	L	Н	L	L	L
L	Н	Н	L	Н	L	Н	L	L	L	Н	L	L
L	Н	Н	Н	L	L	L	Н	L	L	L	Н	L
L	Н	Н	Н	Н	L	L	L	Н	L	L	L	Н
L	L	Н	L	L	L	L	L	L	Н	L	L	L
L	Н	L	L	L	Н	L	L	L	L	L	L	L
Н	Х	Х	Х	Х	L	L	L	L	L	L	L	L



ON Semiconductor

http://onsemi.com

MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620 MC10172L AWLYYWW



PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10172L	CDIP-16	25 Units / Rail
MC10172P	PDIP-16	25 Units / Rail
MC10172FN	PLCC-20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

				Test Limits							
Characteristic			Pin Under	−30°C		+25°C			+85°C		1
		Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply Drain Current		ΙΕ	8		85		65	77		85	mAdc
Input Current		linH	14		350			220		220	μAdc
		linL	14	0.5		0.5			0.3		μAdc
Output Voltag	ge Logic 1	Voн	6 13	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vdc
Output Voltag	ge Logic 0	VOL	13	-1.890	-1.675	-1.850		-1.650	-1.825	-1.615	Vdc
Threshold Vol	Itage Logic 1	Vона	6 13	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		Vdc
Threshold Voltage Logic 0		VOLA	6 13		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	Vdc
Switching Tim	nes (50Ω Load)										ns
Propagation [Delay	t ₇₊₆ - t ₇₋₆₊ t ₇₊₁₃ - t ₇₋₁₃₊	6 6 13 13	1.5 1.5 1.5 1.5	6.2 6.2 6.2 6.2	1.5 1.5 1.5 1.5	4.0 4.0 4.0 4.0	6.0 6.0 6.0 6.0	1.5 1.5 1.5 1.5	6.4 6.4 6.4 6.4	
Rise Time	(20 to 80%)	^t 6+ ^t 13+	6 13	1.0 1.0	3.3 3.3	1.1 1.1	2.0 2.0	3.3 3.3	1.1 1.1	3.4 3.4	
Fall Time	(20 to 80%)	t ₆₋ t ₁₃₋	6 13	1.0 1.0	3.3 3.3	1.1 1.1	2.0 2.0	3.3 3.3	1.1 1.1	3.4 3.4	

ELECTRICAL CHARACTERISTICS (continued)

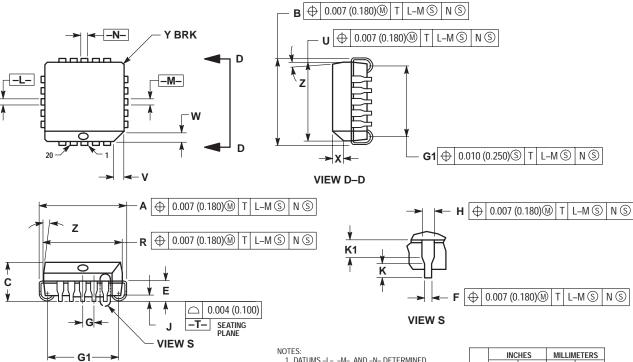
					TEST VOL	TAGE VALU	ES (Volts)		
	V _{IHmax}	V _{ILmin}	VIHAmin	V _{ILAmax}	VEE				
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
	-0.810	-1.850	-1.105	-1.475	-5.2	1			
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
			Pin	TEST V	OLTAGE APF	LIED TO PI	NS LISTED B	ELOW	1
Character	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	VEE	(VCC)	
Power Supply Drain	Current	ΙΕ	8					8	1, 16
Input Current		l _{in} H	14	14				8	1, 16
		linL	14		14			8	1, 16
Output Voltage	Logic 1	Vон	6 13	2 14				8 8	1, 16 1, 16
Output Voltage	Logic 0	VOL	13	15	2,7,9,14			8	1, 16
Threshold Voltage	Logic 1	Vона	6 13			2 14		8 8	1, 16 1, 16
Threshold Voltage	Logic 0	VOLA	6 13		2,9,14 2,7,14		7 9	8 8	1, 16 1, 16
Switching Times	(50Ω Load)			+1.11V	+0.31V	Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay		t ₇₊₆ - t ₇₋₆₊ t ₇₊₁₃ - t ₇₋₁₃₊	6 6 13 13	2 2 14 14	9, 14 9, 14 2, 9 2,9	7 7 7 7	6 6 13 13	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Rise Time	(20 to 80%)	^t 6+ ^t 13+	6 13	2 14	9, 14 2, 9	7 7	6 13	8 8	1, 16 1, 16
Fall Time	(20 to 80%)	t ₆₋ t ₁₃₋	6 13	2 14	9, 14 2, 9	7 7	6 13	8 8	1, 16 1, 16

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



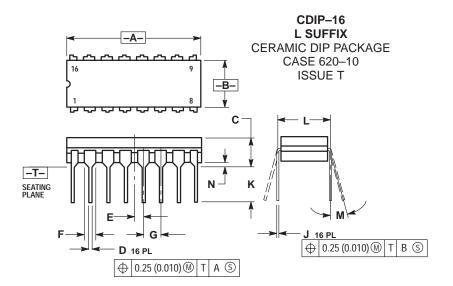
⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

- DATUMS -L-, -M-, AND -N- DETERMINED
 WHERE TOP OF LEAD SHOULDER EXITS PLASTIC WILLY LOVE LEAD STOUDER EXTENSIVE SOLUTION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 4. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.385	0.395	9.78	10.03		
В	0.385	0.395	9.78	10.03		
С	0.165	0.180	4.20	4.57		
Ε	0.090	0.110	2.29	2.79		
F	0.013	0.019	0.33	0.48		
G	0.050	BSC	1.27	BSC		
Н	0.026	0.032	0.66	0.81		
J	0.020		0.51			
K	0.025		0.64			
R	0.350	0.356	8.89	9.04		
U	0.350	0.356	8.89	9.04		
٧	0.042	0.048	1.07	1.21		
W	0.042	0.048	1.07	1.21		
Χ	0.042	0.056	1.07	1.42		
Υ		0.020		0.50		
Z	2°	10 °	2 °	10 °		
G1	0.310	0.330	7.88	8.38		
K1	0.040		1.02			

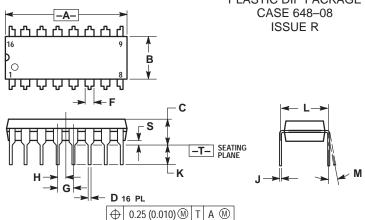
PACKAGE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Ε	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62 BSC		
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

Notes

Notes

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